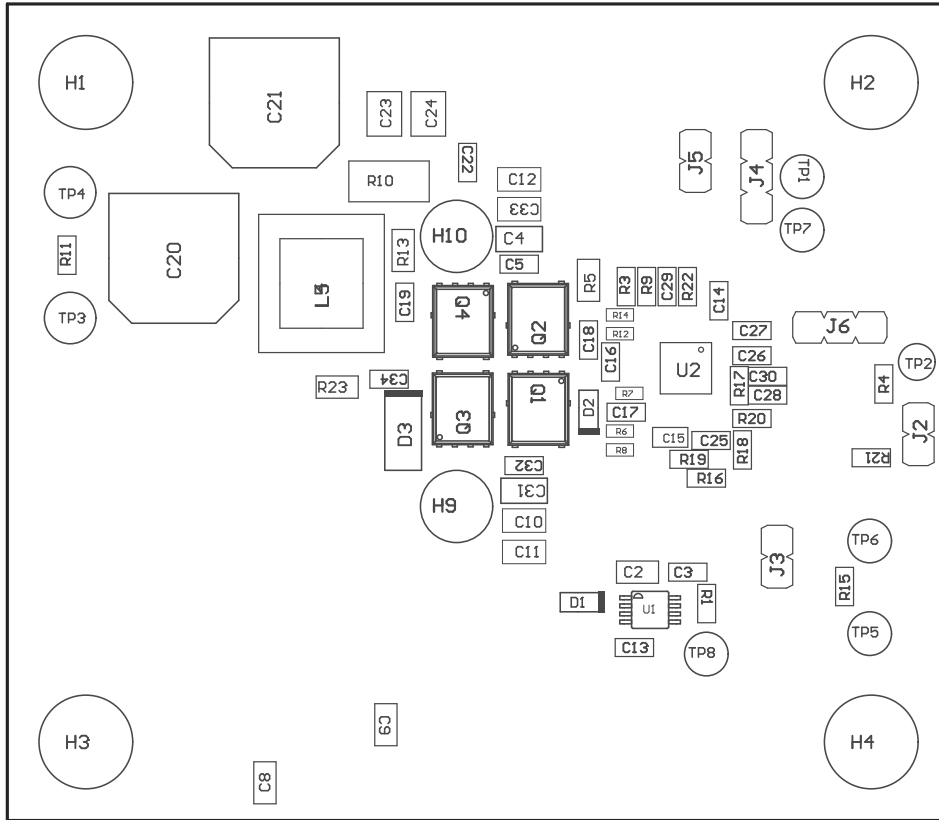


- ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ5 ■ Install Shunt Jumper SH-J1 onto J5
- ZZ6 ■ Install Shunt Jumper SH-J3 onto J4 pin 2-3.
- ZZ7 ■ Install Shunt Jumper SH-J4 onto J6 pins 1-2.
- ZZ8 ■ Install Shunt Jumper SH-J6 onto J3.

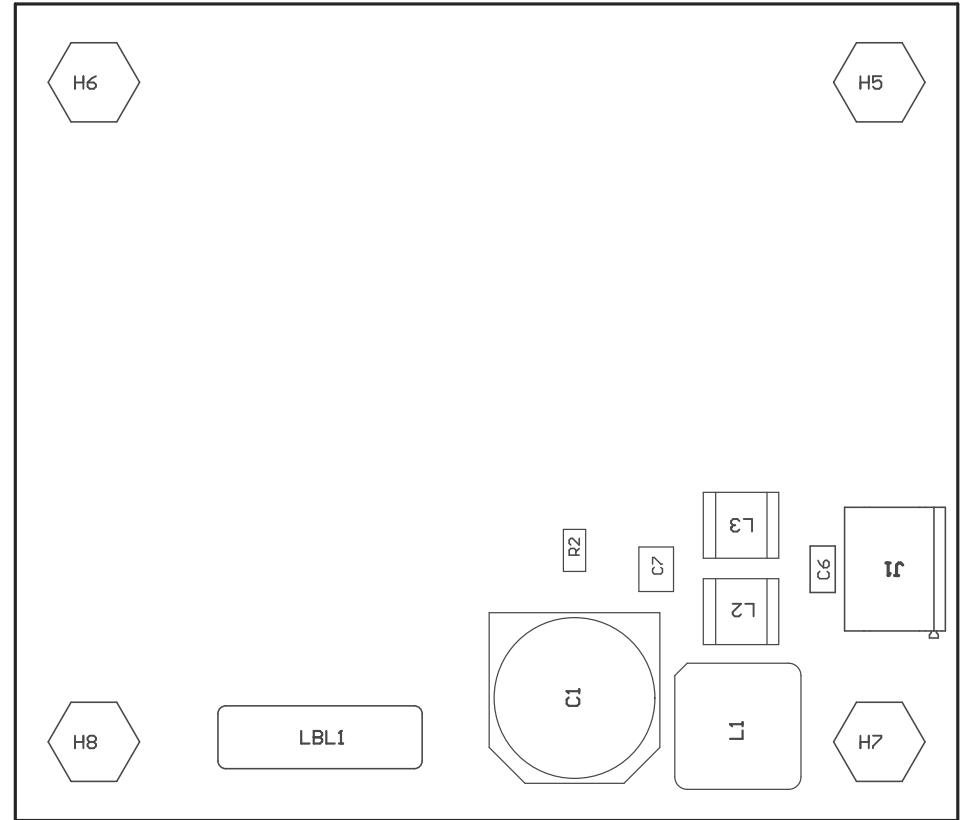
- ZX1 ■ VIN = 8 - 27VDC
- ZX3 ■ VOUT = 3.3VDC
- ZX2 ■ Fsw = 2.2MHz



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
	TID #: PMP20387		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/3/2017	1:23:23 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20387	REV: A	SVN REV: Not In VersionControl
	TID #: PMP20387		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/3/2017 1:23:26 PM		TEXAS INSTRUMENTS

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